ispGAL22V10

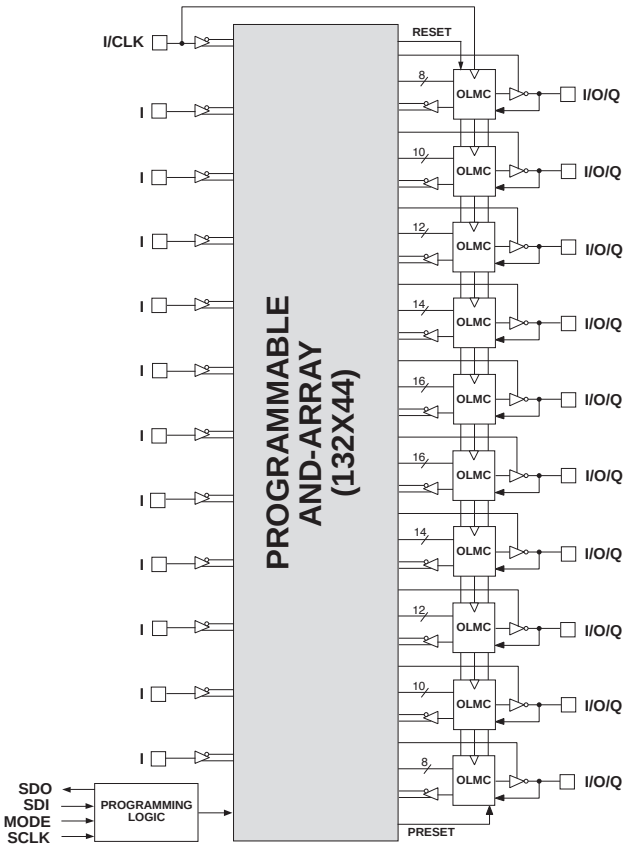
In-System Programmable E²CMOS PLD Generic Array Logic™

Lead-Free Package Options Available!

Features

- IN-SYSTEM PROGRAMMABLE™ (5-V ONLY)
  - — 4-Wire Serial Programming Interface
  - — Minimum 10,000 Program/Erase Cycles
  - — Built-in Pull-Down on SDI Pin Eliminates Discrete Resistor on Board (ispGAL22V10C Only)
- HIGH PERFORMANCE E²CMOS® TECHNOLOGY
  - — 7.5 ns Maximum Propagation Delay
  - — Fmax = 111 MHz
  - — 5 ns Maximum from Clock Input to Data Output
  - — UltraMOS® Advanced CMOS Technology
- ACTIVE PULL-UPS ON ALL LOGIC INPUT AND I/O PINS
- COMPATIBLE WITH STANDARD 22V10 DEVICES
  - — Fully Function/Fuse-Map/Parametric Compatible with Bipolar and CMOS 22V10 Devices
- E² CELL TECHNOLOGY
  - — In-System Programmable Logic
  - — 100% Tested/100% Yields
  - — High Speed Electrical Erasure (<100ms)
  - — 20 Year Data Retention
- TEN OUTPUT LOGIC MACROCELLS
  - — Maximum Flexibility for Complex Logic Designs
- APPLICATIONS INCLUDE:
  - — DMA Control
  - — State Machine Control
  - — High Speed Graphics Processing
  - — Software-Driven Hardware Configuration
- ELECTRONIC SIGNATURE FOR IDENTIFICATION
- LEAD-FREE PACKAGE OPTIONS

Functional Block Diagram



Description

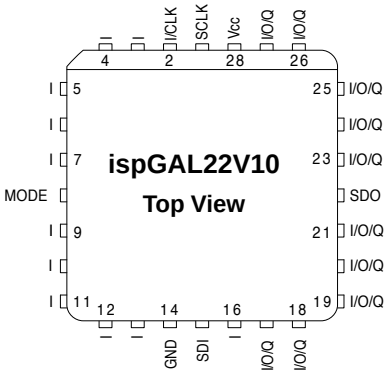
The ispGAL22V10, at 7.5ns maximum propagation delay time, combines a high performance CMOS process with Electrically Erasable (E²) floating gate technology to provide the industry's first in-system programmable 22V10 device. E² technology offers high speed (<100ms) erase times, providing the ability to reprogram or reconfigure the device quickly and efficiently.

The generic architecture provides maximum design flexibility by allowing the Output Logic Macrocell (OLMC) to be configured by the user. The ispGAL22V10 is fully function/fuse map/parametric compatible with standard bipolar and CMOS 22V10 devices. The standard PLCC package provides the same functional pinout as the standard 22V10 PLCC package with No-Connect pins being used for the ISP interface signals.

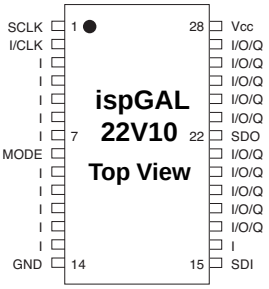
Unique test circuitry and reprogrammable cells allow complete AC, DC, and functional testing during manufacture. As a result, Lattice Semiconductor delivers 100% field programmability and functionality of all GAL products. In addition, 10,000 erase/write cycles and data retention in excess of 20 years are specified.

Pin Configuration

PLCC



SSOP



Select devices have been discontinued. See Ordering Information section for product status.

LATTICE SEMICONDUCTOR CORP

Ordering Information

Conventional Packaging
Commercial Grade Specifications

Tpd (ns)	Tsu (ns)	Tco (ns)	Icc (mA)	Ordering #	Package
7.5	6.5	5	140	ispGAL22V10C-7LJ[1]	28-Lead PLCC
				ispGAL22V10C-7LK	28-Lead SSOP
10	7	7	140	ispGAL22V10C-10LJ	28-Lead PLCC
				ispGAL22V10C-10LK	28-Lead SSOP
15	10	8	140	ispGAL22V10C-15LJ	28-Lead PLCC
				ispGAL22V10C-15LK	28-Lead SSOP

Industrial Grade Specifications

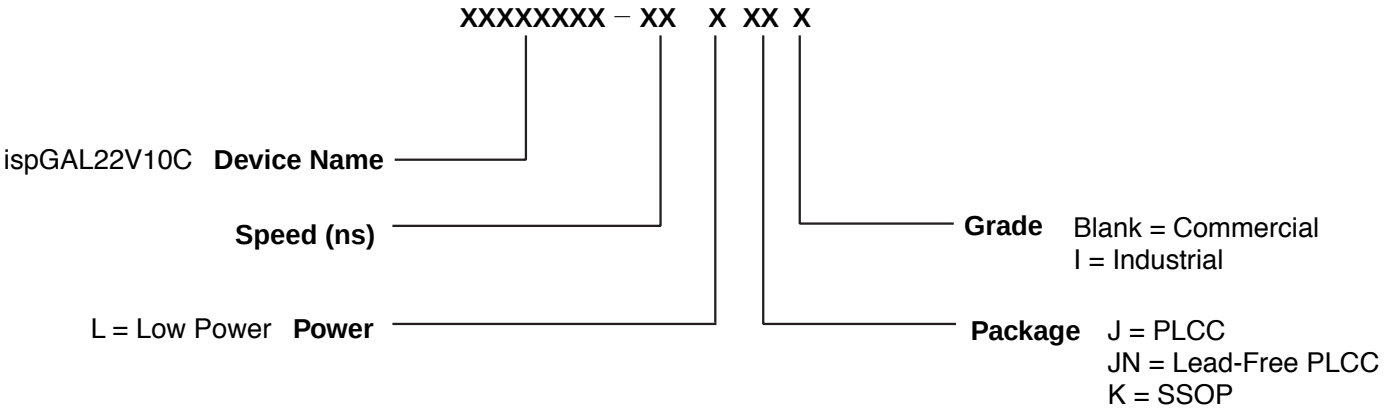
Tpd (ns)	Tsu (ns)	Tco (ns)	Icc (mA)	Ordering #	Package
15	10	8	165	ispGAL22V10C-15LJI	28-Lead PLCC
				ispGAL22V10C-15LKI	28-Lead SSOP

Lead-Free Packaging
Commercial Grade Specifications

Tpd (ns)	Tsu (ns)	Tco (ns)	Icc (mA)	Ordering #	Package
7.5	6.5	5	140	ispGAL22V10C-7LJN[1]	Lead-Free 28-Lead PLCC
10	7	7	140	ispGAL22V10C-10LJN	Lead-Free 28-Lead PLCC
15	10	8	140	ispGAL22V10C-15LJN	Lead-Free 28-Lead PLCC

1. Discontinued per PCN #06-07. Contact Rochester Electronics for available inventory.

Part Number Description



Select devices have been discontinued. See Ordering Information section for product status.

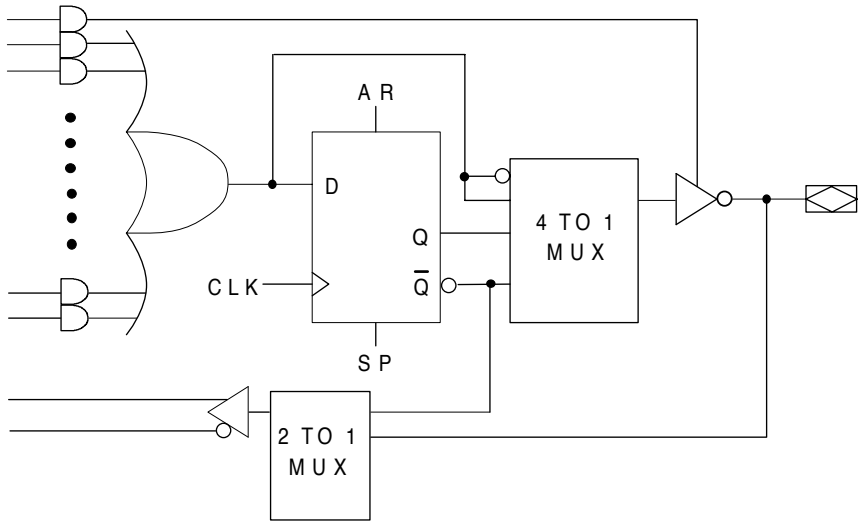
Output Logic Macrocell (OLMC)

The ispGAL22V10 has a variable number of product terms per OLMC. Of the ten available OLMCs, two OLMCs have access to eight product terms (pins 17 and 27), two have ten product terms (pins 18 and 26), two have twelve product terms (pins 19 and 25), two have fourteen product terms (pins 20 and 24), and two OLMCs have sixteen product terms (pins 21 and 23). In addition to the product terms available for logic, each OLMC has an additional product-term dedicated to output enable control.

The output polarity of each OLMC can be individually programmed to be true or inverting, in either combinatorial or registered mode. This allows each output to be individually configured as either active high or active low.

The ispGAL22V10 has a product term for Asynchronous Reset (AR) and a product term for Synchronous Preset (SP). These two product terms are common to all registered OLMCs. The Asynchronous Reset sets all registers to zero any time this dedicated product term is asserted. The Synchronous Preset sets all registers to a logic one on the rising edge of the next clock pulse after this product term is asserted.

NOTE: The AR and SP product terms will force the Q output of the flip-flop into the same state regardless of the polarity of the output. Therefore, a reset operation, which sets the register output to a zero, may result in either a high or low at the output pin, depending on the pin polarity chosen.



ispGAL22V10 OUTPUT LOGIC MACROCELL (OLMC)

Output Logic Macrocell Configurations

Each of the Macrocells of the ispGAL22V10 has two primary functional modes: registered, and combinatorial I/O. The modes and the output polarity are set by two bits (SO and S1), which are normally controlled by the logic compiler. Each of these two primary modes, and the bit settings required to enable them, are described below and on the following page.

REGISTERED

In registered mode the output pin associated with an individual OLMC is driven by the Q output of that OLMC's D-type flip-flop. Logic polarity of the output signal at the pin may be selected by specifying that the output buffer drive either true (active high) or inverted (active low). Output tri-state control is available as an individual product-term for each OLMC, and can therefore be defined by a logic equation. The D flip-flop's /Q output is fed back into the AND array, with both the true and complement of the feedback available as inputs to the AND array.

NOTE: In registered mode, the feedback is from the /Q output of the register, and not from the pin; therefore, a pin defined as registered is an output only, and cannot be used for dynamic I/O, as can the combinatorial pins.

COMBINATORIAL I/O

In combinatorial mode the pin associated with an individual OLMC is driven by the output of the sum term gate. Logic polarity of the output signal at the pin may be selected by specifying that the output buffer drive either true (active high) or inverted (active low). Output tri-state control is available as an individual product-term for each output, and may be individually set by the compiler as either "on" (dedicated output), "off" (dedicated input), or "product-term driven" (dynamic I/O). Feedback into the AND array is from the pin side of the output enable buffer. Both polarities (true and inverted) of the pin are fed back into the AND array.

Absolute Maximum Ratings(1)

Supply voltage V_{CC} ..... -0.5 to +7V

Input voltage applied ..... -2.5 to V_{CC} +1.0V
Off-state output voltage applied ..... -2.5 to V_{CC} +1.0V
Storage Temperature ..... -65 to 150°C
Ambient Temperature with
Power Applied ..... -55 to 125°C

1. Stresses above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress only ratings and functional operation of the device at these or at any other conditions above those indicated in the operational sections of this specification is not implied (while programming, follow the programming specifications).

Recommended Operating Conditions

Commercial Devices:
Ambient Temperature (T_A) ..... 0 to +75°C
Supply voltage (V_{CC})
with Respect to Ground ..... +4.75 to +5.25V

Industrial Devices:
Ambient Temperature (T_A) ..... -40 to 85°C
Supply voltage (V_{CC})
with Respect to Ground ..... +4.50 to +5.50V

DC Electrical Characteristics

Over Recommended Operating Conditions (Unless Otherwise Specified)

SYMBOL	PARAMETER	CONDITION	MIN.	TYP.[4]	MAX.	UNITS
V_{IL}	Input Low Voltage		Vss – 0.5	—	0.8	V
V_{IH}	Input High Voltage		2.0	—	Vcc+1	V
I_{IL}	Input or I/O Low Leakage Current[1]	$0V \le V_{IN} \le V_{IL}$ (MAX.)	—	—	–100	µA
	SDI Low Leakage Current[2]	$0V \le V_{IN} \le V_{IL}$ (MAX.)	—	—	250	µA
I_{IH}	Input or I/O High Leakage Current	$3.5V \le V_{IN} \le V_{CC}$	—	—	10	µA
	SDI High Leakage Current[2]	$V_{IN} = V_{OH}$ (MIN.)	—	—	1	mA
V_{OL}	Output Low Voltage	I_{OL} = MAX. Vin = V_{IL} or V_{IH}	—	—	0.5	V
V_{OH}	Output High Voltage	I_{OH} = MAX. Vin = V_{IL} or V_{IH}	2.4	—	—	V
I_{OL}	Low Level Output Current		—	—	16	mA
I_{OH}	High Level Output Current		—	—	–3.2	mA
I_{OS}[3]	Output Short Circuit Current	V_{CC} = 5V V_{OUT} = 0.5V T_A = 25°C	–30	—	–130	mA

COMMERCIAL

I_{CC}	Operating Power Supply Current	V_{IL} = 0.5V V_{IH} = 3.0V f_{toggle} = 15MHz Outputs Open	L -7/-10/-15	—	90	140	mA

INDUSTRIAL

I_{CC}	Operating Power Supply Current	V_{IL} = 0.5V V_{IH} = 3.0V f_{toggle} = 15MHz Outputs Open	L -15	—	90	165	mA

1) The leakage current is due to the internal pull-up on all pins (except SDI on ispGAL22V10C). See **Input Buffer** section for more information.
2) The leakage current is due to the internal pull-down on the SDI pin (ispGAL22V10C only). See **Input Buffer** section for more information.
3) One output at a time for a maximum duration of one second. Vout = 0.5V was selected to avoid test problems caused by tester ground degradation. Characterized but not 100% tested.
4) Typical values are at Vcc = 5V and T_A = 25 °C

AC Switching Characteristics

Over Recommended Operating Conditions

PARAMETER	TEST COND.[1]	DESCRIPTION	COM -7 MIN.	COM -7 MAX.	COM -10 MIN.	COM -10 MAX.	COM/IND -15 MIN.	COM/IND -15 MAX.	UNITS
t_{pd}	A	Input or I/O to Combinatorial Output	—	7.5	—	10	—	15	ns
t_{co}	A	Clock to Output Delay	—	5	—	7	—	8	ns
t_{cf}[2]	—	Clock to Feedback Delay	—	2.5	—	2.5	—	2.5	ns
t_{su_1}	—	Setup Time, Input or Feedback before Clock↑	6.5	—	7		10	—	ns
t_{su_2}	—	Setup Time, SP before Clock↑	10	—	10	—	10	—	ns
t_h	—	Hold Time, Input or Feedback after Clock↑	0	—	0	—	0	—	ns
f_{max}[3]	A	Maximum Clock Frequency with External Feedback, 1/(tsu + tco)	87	—	71.4	—	55.5	—	MHz
	A	Maximum Clock Frequency with Internal Feedback, 1/(tsu + tcf)	111	—	105	—	80	—	MHz
	A	Maximum Clock Frequency with No Feedback	111	—	105	—	83.3	—	MHz
t_{wh}	—	Clock Pulse Duration, High	4	—	4	—	6	—	ns
t_{wl}	—	Clock Pulse Duration, Low	4	—	4	—	6	—	ns
t_{en}	B	Input or I/O to Output Enabled	—	8	—	10	—	15	ns
t_{dis}	C	Input or I/O to Output Disabled	—	8	—	10	—	15	ns
t_{ar}	A	Input or I/O to Asynchronous Reset of Register	—	13	—	13	—	20	ns
t_{arw}	—	Asynchronous Reset Pulse Duration	8	—	8	—	15	—	ns
t_{arr}	—	Asynchronous Reset to Clock Recovery Time	8	—	8	—	10	—	ns
t_{spr}	—	Synchronous Preset to Clock Recovery Time	10	—	10	—	10	—	ns

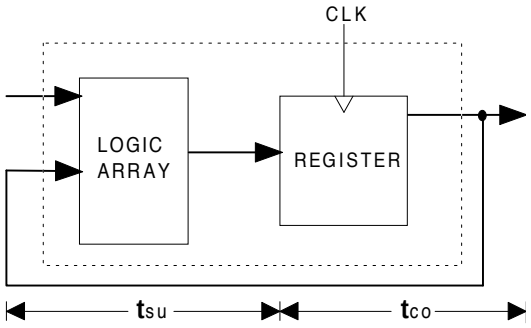
1) Refer to **Switching Test Conditions** section.
2) Calculated from **f**max with internal feedback. Refer to **fmax Description** section.
3) Refer to **fmax Description** section.

Capacitance (T_A = 25°C, f = 1.0MHz)

SYMBOL	PARAMETER	MAXIMUM*	UNITS	TEST CONDITIONS
C_I	Input Capacitance	8	pF	V_{CC} = 5.0V, V_I = 2.0V
$C_{I/O}$	I/O Capacitance	8	pF	V_{CC} = 5.0V, $V_{I/O}$ = 2.0V

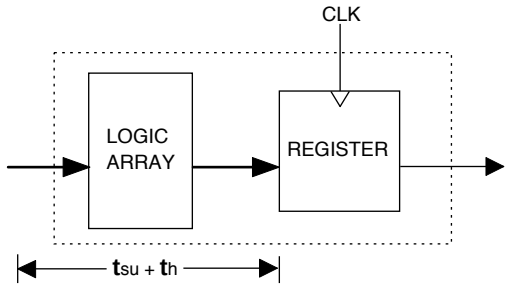
*Characterized but not 100% tested.

fmax Descriptions



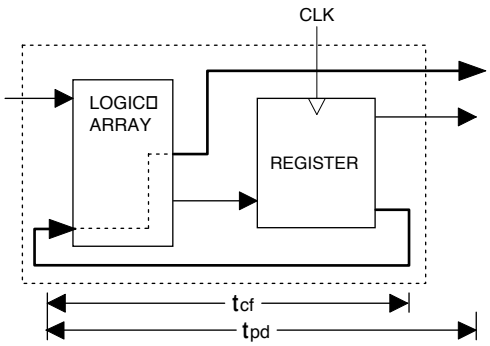
fmax with External Feedback 1/(tsu+tco)

Note: fmax with external feedback is calculated from measured tsu and tco.



fmax with No Feedback

Note: fmax with no feedback may be less than 1/twh + twl. This is to allow for a clock duty cycle of other than 50%.



fmax with Internal Feedback 1/(tsu+tcf)

Note: tcf is a calculated value, derived by subtracting tsu from the period of fmax w/internal feedback (tcf = 1/fmax - tsu). The value of tcf is used primarily when calculating the delay from clocking a register to a combinatorial output (through registered feedback), as shown above. For example, the timing from clock to a combinatorial output is equal to tcf + tpd.

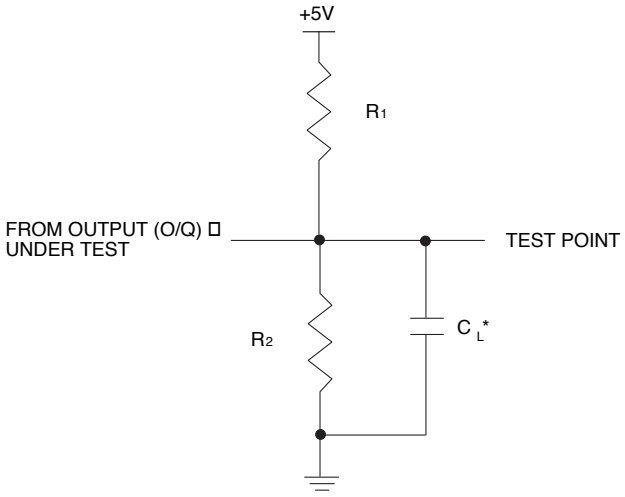
Switching Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise and Fall Times	3ns 10% – 90%
Input Timing Reference Levels	1.5V
Output Timing Reference Levels	1.5V
Output Load	See Figure

3-state levels are measured 0.5V from steady-state active level.

Output Load Conditions (see figure)

Test Condition		R1	R2	CL
A		300Ω	390Ω	50pF
B	Active High	∞	390Ω	50pF
	Active Low	300Ω	390Ω	50pF
C	Active High	∞	390Ω	5pF
	Active Low	300Ω	390Ω	5pF



*C_L INCLUDES TEST FIXTURE AND PROBE CAPACITANCE